



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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## Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- For Use in Low-Voltage, High-Frequency Inverters, ORing, and Polarity Protection Applications
- High Forward Surge Current Capability
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

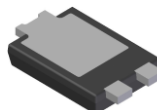
## Mechanical Data

- Case: POWERDI®5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ③
- Polarity: See Diagram
- Weight: 0.096 grams (Approximate)

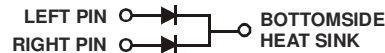
POWERDI®5



Top View



Bottom View



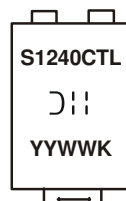
**Note:** Pins Left & Right must be electrically connected at the printed circuit board.


## Ordering Information (Note 4)

Part Number	Case	Packaging
PDS1240CTL-13	POWERDI®5	5,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com>.

## Marking Information



S1240CTL = Product Type Marking Code  
 = Manufacturers' Code Marking  
 YYWW = Date Code Marking  
 YY = Last Digit of Year (ex: 15 for 2015)  
 WW = Week Code (01 - 53)  
 K = Factory Designator Code

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	40	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
Average Rectified Output Current	I <sub>O</sub>	6	A
per element		12	
total device			
Non-Repetitive Peak Forward Surge Current, per element	I <sub>FSM</sub>	150	A
8.3ms Single half sine-wave Superimposed on Rated Load			

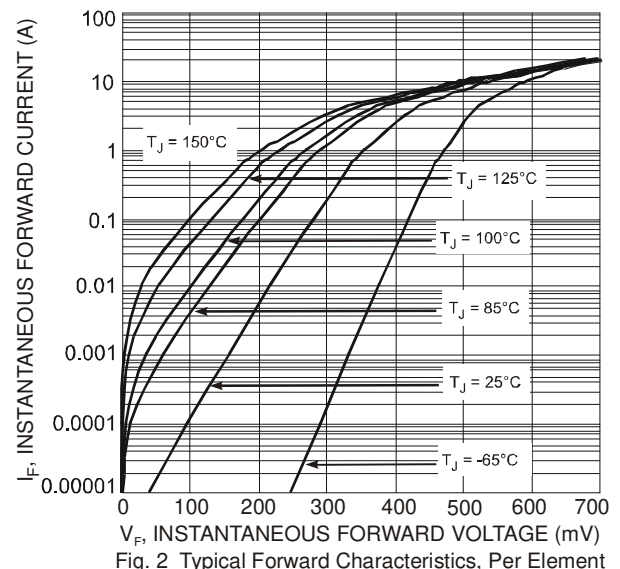
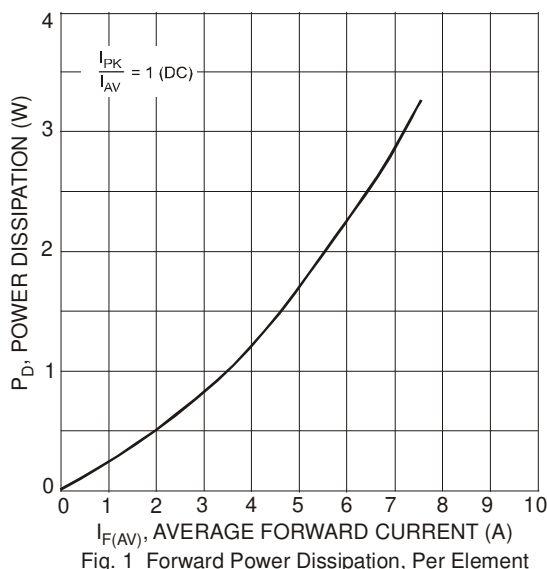
## Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point	R <sub>θJS</sub>	—	2.0	°C/W
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	95	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	75	—	°C/W
Thermal Resistance Junction to Ambient Air (Note 7)	R <sub>θJA</sub>	50	—	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150		°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V <sub>(BR)R</sub>	40	—	—	V	I <sub>R</sub> = 500μA
Forward Voltage Per Element	V <sub>F</sub>	—	—	0.52	V	I <sub>F</sub> = 6A, T <sub>J</sub> = +25°C
		—	—	0.45		I <sub>F</sub> = 6A, T <sub>J</sub> = +100°C
Reverse Leakage Current (Note 8) Per Element	I <sub>R</sub>	—	—	350	μA	V <sub>R</sub> = 40V, T <sub>J</sub> = +25°C
		—	—	20	mA	V <sub>R</sub> = 40V, T <sub>J</sub> = +100°C

- Notes:
- FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
  - Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
  - Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
  - Short duration pulse test used to minimize self-heating effect.





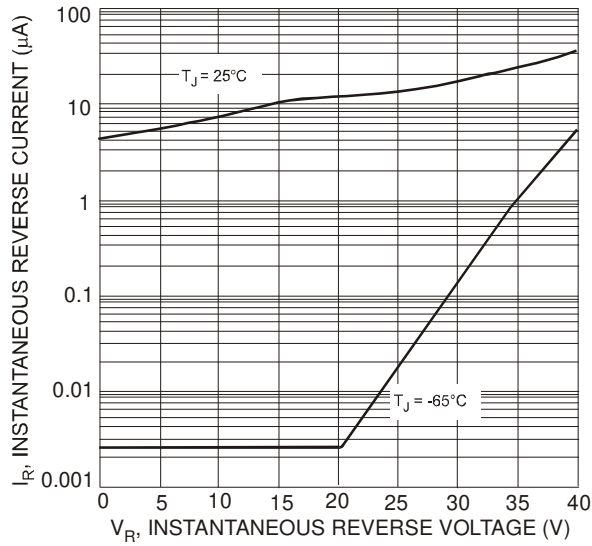


Fig. 3 Typical Reverse Characteristics, Per Element

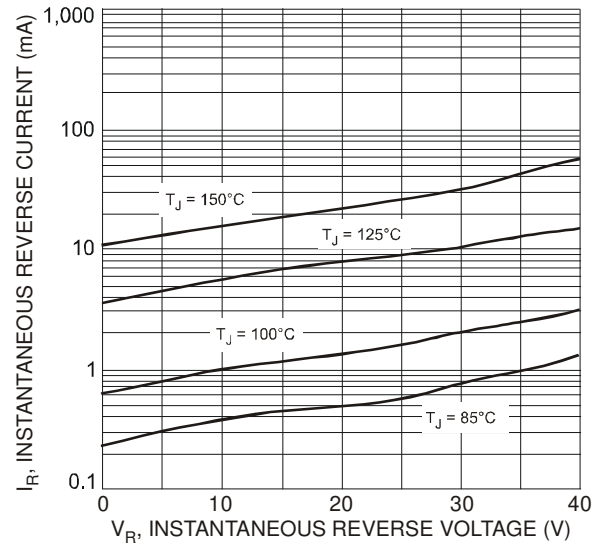


Fig. 4 Typical Reverse Characteristics, Per Element

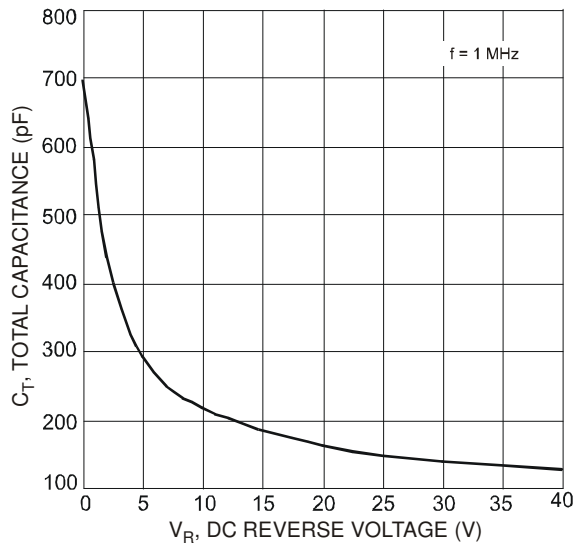


Fig. 5 Total Capacitance vs. Reverse Voltage, Per Element

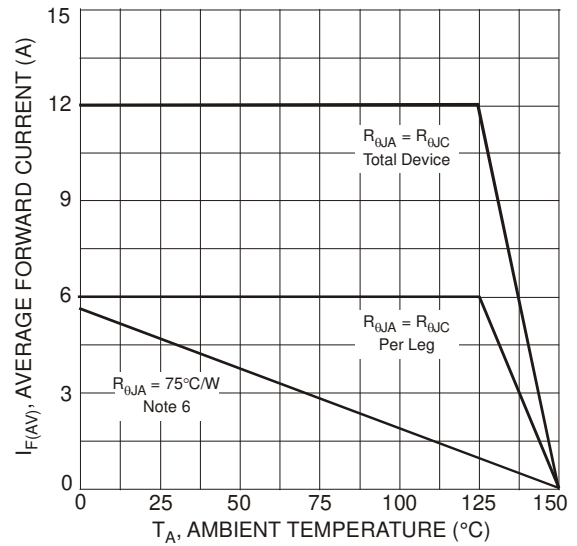


Fig. 6 Forward Current Derating Curve

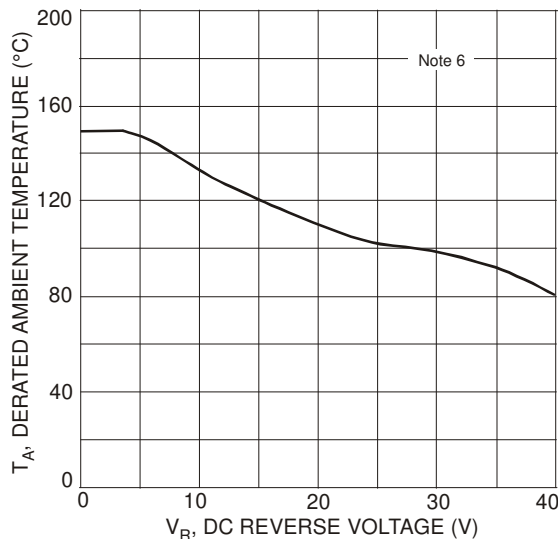
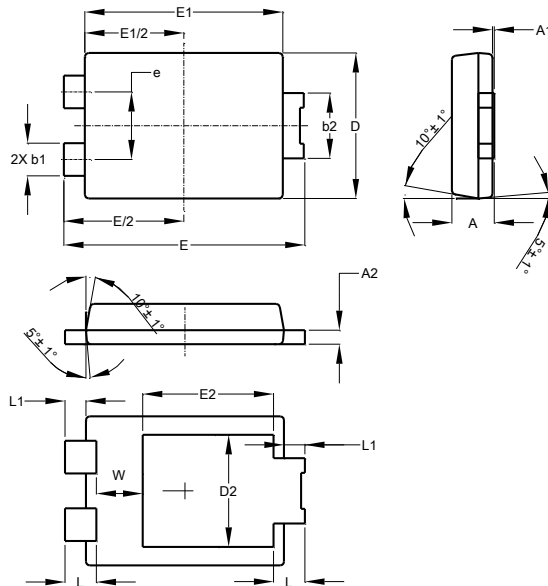


Fig. 7 Operating Temperature Derating, Per Element

## Package Outline Dimensions

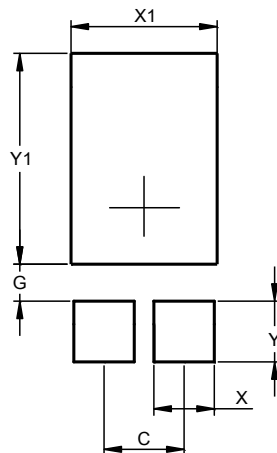
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



POWERDI <sup>®</sup> 5			
Dim	Min	Max	Typ
A	1.05	1.15	1.10
A1	0.00	0.05	-
A2	0.33	0.43	0.381
b1	0.80	0.99	0.89
b2	1.70	1.88	1.78
D	3.90	4.05	3.966
D2	-	-	3.054
E	6.40	6.60	6.504
e	-	-	1.84
E1	5.30	5.45	5.37
E2	-	-	3.549
L	0.75	0.95	0.85
L1	0.50	0.65	0.57
W	1.10	1.41	1.255
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	1.840
G	0.852
X	1.390
X1	3.360
Y	1.400
Y1	4.860

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